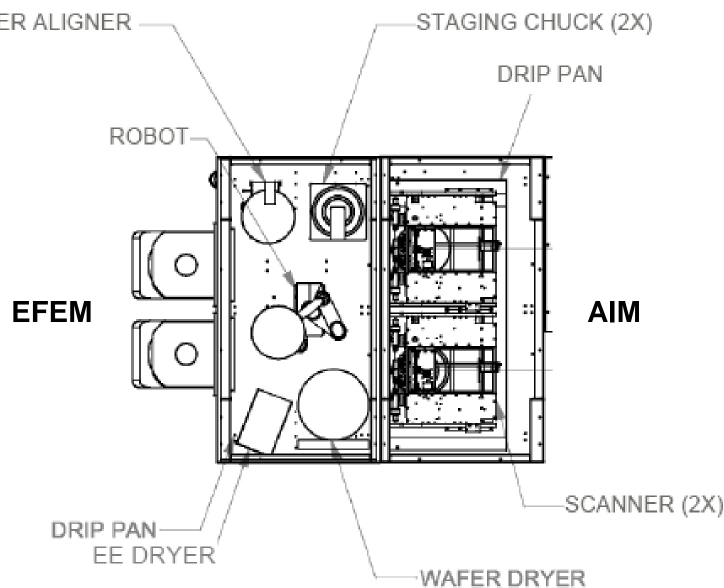
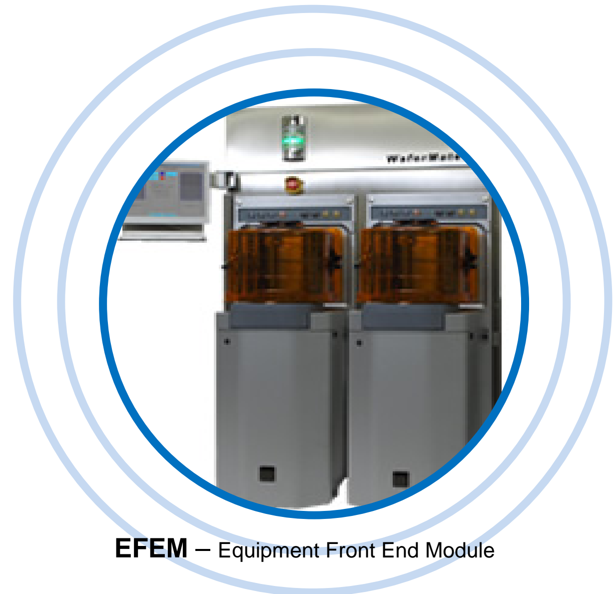
Sonoscan®
Sound Technology With Vision

AW300™ Series C-SAM®

Automated Wafer Bond Inspection



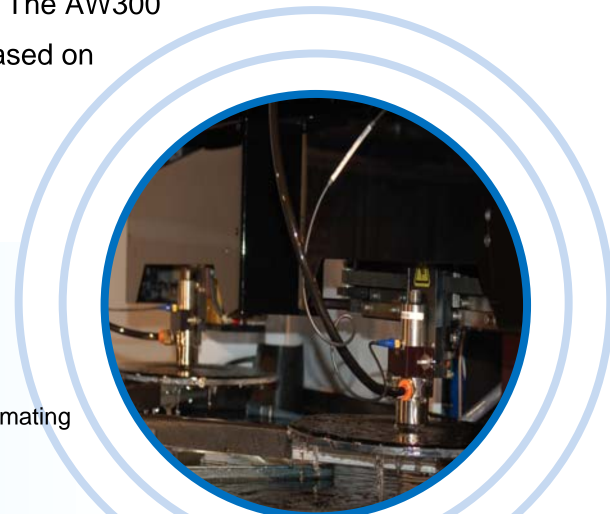


EFEM – Equipment Front End Module

AIM – Acoustic Imaging Module

Operator-Free Inspection, Analysis and Sorting

The AW300™ Series is an advanced instrument specialized for wafer bond applications. It delivers a better than 5 micron sensitivity, a throughput that is approximately two times faster than competitive systems, and a non-immersion scanner that eliminates false positives due to DI water ingression. The AW300 Series automatically handles, inspects and sorts bonded wafers based on user-defined accept/reject criteria.



Dual Non-Immersion Imaging
via Sonoscan's Waterfall™ transducer reduces contamination and false bond indications

Features

- Sonoscan's Waterfall™ transducer provides non-immersion scanning which minimizes risks of contamination and false bond indications
- Dual vacuum assisted stages to maximize total throughput by efficiently automating the entire inspection process—including aligning, delivery, drying and sorting
- Dual loadports for larger batch capacity
- Loadports for 300 mm FOUP or FSOB carriers available
- Sonoscan automated analysis software accurately determines percent bond/nonbonded, void size and count, and automatic accept/reject based on user-defined criteria
- 500 MHz bandwidth pulser/receiver and ultra-high resolution transducers are designed and manufactured by Sonoscan for optimum performance and to generate superior images
- Class 1000 clean room rated